



Material Content Data Sheet



Sales Product Name	TLE4968-1M			Issued	22. October 2018			
MA#	MA003975690							
Package	PG-SOT23-3-15			Weight*	9.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35596	35596
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365603	367144
	noble metal	gold	7440-57-5	0.018	0.19	0.19	1854	1854
	encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5463
encapsulation	plastics	epoxy resin	-	1.153	11.75		117459	
	inorganic material	silicondioxide	60676-86-0	4.157	42.33	54.63	423398	546320
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15241	15241
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15133	15133
glue	plastics	epoxy resin	-	0.032	0.33		3275	
	noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18712
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com